



November 14, 2017

NEWS RELEASE

Additional Increase in Production Capacity of Ultra-Thin Copper Foil with Carrier

- A third increase in monthly production capacity to 3.9 million m² -

Mitsui Mining & Smelting Co., Ltd. (President: (President: Keiji Nishida; “Mitsui Kinzoku,” hereinafter) is pleased to announce that it has decided to increase the monthly production capacity of ultra-thin copper foil with carrier to 3.9 million m².

Mitsui Kinzoku’s MicroThinTM ultra-thin copper foil with carrier features a combination of thickness ranging from 1.5 μm to 5 μm, suited for the formation of fine circuits, and multiple fine roughening processes. It has already found application with motherboards for smartphones, or HDI printed circuit boards, in addition to conventional packaged circuit boards.

As announced in the press release on May 15, 2017, Mitsui Kinzoku decided to increase the monthly MicroThinTM production capacity at the Malaysian plant (Mitsui Copper Foil (Malaysia) SDN. BHD.) to 1.8 million m². Given that demand is expected to continue to grow over the coming fiscal years, a third increase in production capacity at the Malaysian plant will be made. From November 2018, monthly production capacity will stand at 2.4 million m². As a consequence, Mitsui Kinzoku’s total monthly production capacity of the MicroThinTM, including that of its Ageo plant, will rise to 3.9 million m², paving the way for stable supply to meet growing demand.

Under its slogan of Material Intelligence, Mitsui Kinzoku will be working to ensure stable quality and sufficient supply to customers and will in the future adjust its production capacity in response to demand trends.

[Inquiries]

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Mitsui Copper Foil (Malaysia) SDN. BHD.

(Reference)

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| (1) Name | Mitsui Copper Foil (Malaysia) SDN. BHD. |
| (2) Location | Selangor, Malaysia |
| (3) President | Yuji Tejima |
| (4) Established | April 1989 |
| (5) Capital | 330,000,000 Malaysian Ringgit |
| (6) Investment | Mitsui Kinzoku (100%) |
| (7) Business Activities | Manufacturing of copper foil for printed circuit boards |